



Material Content Data Sheet



Sales Product Name		IDH02SG120		Issued		29. August 2013		
MA#		MA000623048						
Package		PG-TO220-2-1		Weight*		1966.13 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.227	0.06		624	
	noble metal	gold	7440-57-5	0.075	0.00		38	
	non noble metal	tin	7440-31-5	0.019	0.00	0.06	10	672
leadframe	non noble metal	iron	7439-89-6	0.753	0.04		383	
	inorganic material	phosphorus	7723-14-0	0.226	0.01		115	
	non noble metal	copper	7440-50-8	751.797	38.25	38.30	382373	382871
wire	non noble metal	aluminium	7429-90-5	0.641	0.03	0.03	326	326
	encapsulation	organic material	carbon black	1333-86-4	9.097	0.46		4627
plastics		epoxy resin	-	100.069	5.09		50896	
inorganic material		silicondioxide	60676-86-0	497.314	25.29	30.84	252940	308463
leadfinish	non noble metal	tin	7440-31-5	14.487	0.74	0.74	7368	7368
plating	non noble metal	nickel	7440-02-0	0.198	0.01		101	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.01	0	101
heatspreader	inorganic material	phosphorus	7723-14-0	0.177	0.01		90	
	non noble metal	iron	7439-89-6	0.590	0.03		300	
	non noble metal	copper	7440-50-8	589.466	29.98	30.02	299809	300200
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

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